



PolyStrata[®] Package

Nuvotronics presents a new state of the art low loss MMIC package. The PolyStrata[®] package complements integrated MMIC performance and can be surface mounted to a PCB using standard SMT processes. This increases the ease of manufacturing while maintaining superior performance in a smaller size compared to other packaging substrates.

Features and Benefits

- Ultra-Low Loss
- Ideal thermal performance due to solid copper construction
- Chip interface compatible with automated Au wire bonding
- PCB interface compatible with standard SMT processes

Applications

- Military
- Space
- Communications
- Instrumentation

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SCAN ME

Standard mmWave Packages

Part Number	Lid	Single Sided Transition Performance			Max Die Size			Package Size			DC Pins	Lead Time (if not in stock)
		Max Frequency (GHz)	Insertion Loss (dB)	Return Loss (dB)	X (mm)	Y (mm)	Z (mm)	X (mm)	Y (mm)	Z (mm)		
PSP1028104*	1028940-007	95	0.65	12	5.71	5.55	0.1	9	9	0.7	16	13 weeks
PSP1028105*	1028940-006	95	0.65	12	4.71	4.55	0.1	8	8	0.7	14	13 weeks
PSP1028106*	1028940-005	95	0.65	12	3.71	3.55	0.1	7	7	0.7	12	13 weeks
PSP1028107*†	1028940-004	95	0.65	12	2.71	2.55	0.1	6	6	0.7	12	13 weeks
PSP1028108*†	1028940-003	95	0.65	12	1.71	1.55	0.1	5	5	0.7	8	13 weeks
PSP1028109*†	1028940-005	50	0.3	12	5	5	0.1	7	7	0.4	12	9 weeks
PSP1028110*	1028940-004	50	0.3	12	4	4	0.1	6	6	0.4	10	9 weeks
PSP1028111*†	1028940-003	50	0.3	12	3	3	0.1	5	5	0.4	8	9 weeks
PSP1028112*	1028940-002	50	0.3	12	2	2	0.1	4	4	0.4	6	9 weeks
PSP1028113*	1028940-001	50	0.3	12	1	1	0.1	3	3	0.4	4	9 weeks

* In development

† Samples available

Device Specific mmWave Packages

Part Number	Matching Device	Manufacturer	Package Size			Lid #	Lead Time
			X	Y	Z		
PSP1025530_002	ALP302	Northrop Grumman	6.34	3.869	1.513	1025503	13 weeks
PSP1029439	TGA2962	Qorvo	5.5	6	1.425	1028940-009	9 weeks